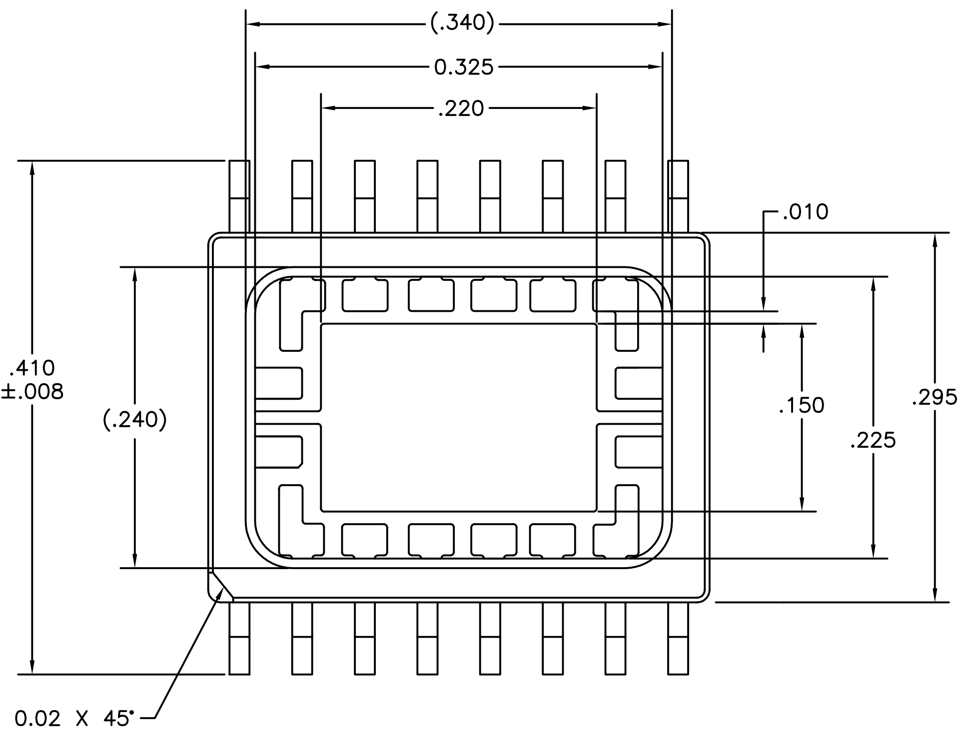
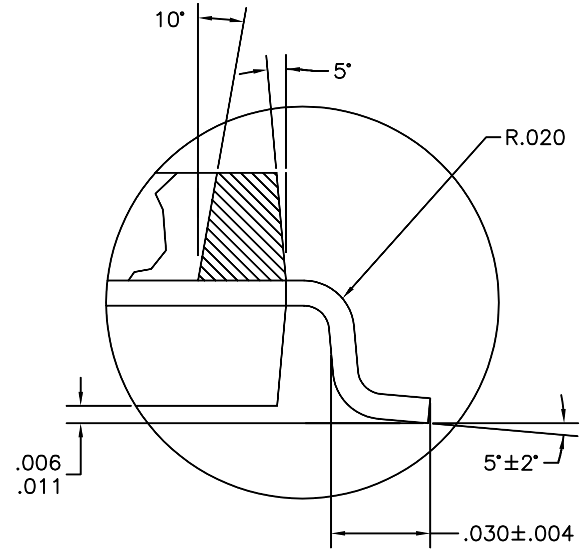
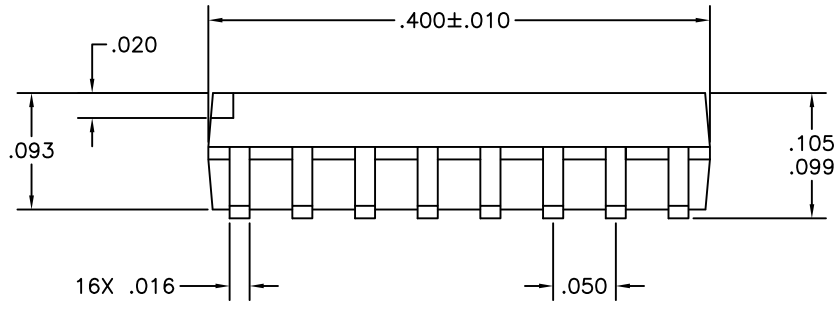
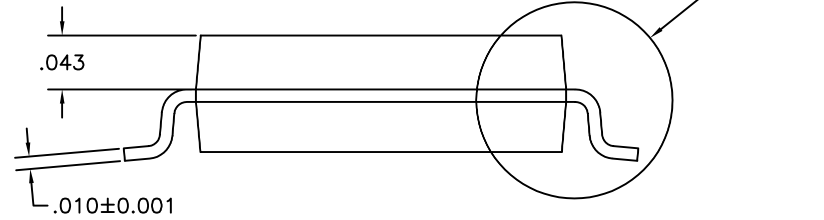




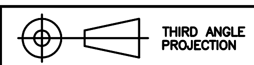




REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10511	11/2/05	PRODUCTION RELEASE	D.BENANDO

NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL Au PLATE.
4. DIE PAD: 0.220 X 0.150
5. UNSPECIFIED RADIUS: R.010 MAX.
6. JEDEC OUTLINE: MS-013



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
X.XX ± 0.01　X.XXXX ±---
X.XXX ± 0.005　ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	11/1/05
APP BY	P. FLASKERUD	DATE	11/1/05
CUSTOMER	---		

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SEMPAC, INC.
Open-Pak™ Technologies
www.sempac.com
568 E. WEDDELL DRIVE, SUITE 5
SUNNYVALE, CALIFORNIA 94089
PHONE: (408) 400-9002　FAX: (408) 400-9006

16 Lead 300 mils SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC300-16-OP-01	2

SCALE NONE | CAD FILE SOIC300-16-OP-01-R2.DWG | SHEET 1 OF 1

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REV 1 ECN 10598